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(54) Title: A WAFER LEVEL PACKAGE AND A METHOD OF FORMING A WAFER LEVEL PACKAGE

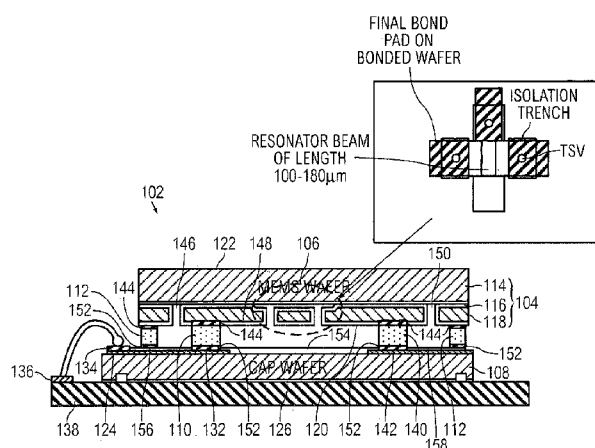


FIGURE 1

(57) Abstract: In an embodiment, a wafer level package may be provided. The wafer level package may include a device wafer including a MEMS device, a cap wafer disposed over the device wafer, at least one first interconnect disposed between the device wafer and the cap wafer and configured to provide an electrical connection between the device wafer and the cap wafer, and a conformal sealing ring disposed between the device wafer and the cap wafer and configured to surround the at least one first interconnect and the MEMS device so as to provide a conformally sealed environment for the at least one first interconnect and the MEMS device, wherein the conformal sealing ring may be configured to conform to a respective suitable surface of the device wafer and the cap wafer when the device wafer may be bonded to the cap wafer. A method of forming a wafer level package may also be provided.





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